

## A. ECAD Design Information

This appendix contains information that supports the development of the PCB ECAD model for this device. It is intended to be used by PCB designers.

### A.1 Part Number Indexing

Orderable Part Number	Number of Pins	Package Type	Package Code/POD Number
R5F10NLEDFB#75	64	LFQFP	PLQP0064KC-A
R5F10NLGDFB#75	64	LFQFP	PLQP0064KC-A
R5F10NMEDFB#75	80	LFQFP	PLQP0080KB-B
R5F10NMGDFB#75	80	LFQFP	PLQP0080KB-B
R5F10NMJDFB#75	80	LFQFP	PLQP0080KB-B
R5F10NMLDFB#70	80	LFQFP	PLQP0080KJ-A
R5F10NPGDFB#75	100	LFQFP	PLQP0100KB-B
R5F10NPJDFB#75	100	LFQFP	PLQP0100KB-B
R5F10NPLDFB#70	100	LFQFP	PLQP0100KB-B
R5F11TLEDFB#75	64	LFQFP	PLQP0064KC-A
R5F11TLGDFB#75	64	LFQFP	PLQP0064KC-A

### A.2 Symbol Pin Information

#### A.2.1 100-LFQFP

Pin Number	Primary Pin Name	Primary Electrical Type	Alternate Pin Name(s)
1	P06	I/O	SI00/RxD0/SDA00/TI03/TO03/TOOLRxD
2	P05	I/O	SCK00/SCL00/TI04/TO04/INTP3
3	P04	I/O	SO10/TxD1/TI05/TO05/INTP4
4	P03	I/O	SI10/RxD1/SDA10/TI06/TO06
5	P02	I/O	SCK10/SCL10/TI07/TO07/INTP5
6	P43	I/O	TI00/TO00/PCLBUZ0
7	P42	I/O	INTP7
8	P41	I/O	TI01/TO01/PCLBUZ1/INTP6
9	P40	I/O	TOOL0
10	P152	I/O	RTCIC2
11	P151	I/O	RTCIC1
12	P150	I/O	RTCCOUT/RTCIC0
13	\RESET	Input	-
14	P122	Input	X2/EXCLK
15	P121	Input	X1
16	P137	Input	INTP0
17	P124	Input	XT2/EXCLKS
18	P123	Input	XT1
19	VRTC	Power	-
20	REGC	Power	-
21	VSS	Power	EVSS0
22	VDD	Power	-
23	EVDD0	Power	-
24	VBAT	Power	-
25	P60	I/O	SCLA0/(TI00)/(TO00)
26	P61	I/O	SDAA0/(TI01)/(TO01)
27	P62	I/O	(TI02)/(TO02)/(RTCCOUT)
28	P127	I/O	CAPH/(TI03)/(TO03)
29	P126	I/O	CAPL/(TI04)/(TO04)
30	VL1	Power	-
31	VL2	Power	-
32	VL4	Power	-
33	P125	I/O	VL3/INTP1/(TI05)/(TO05)
34	P37	I/O	SEG31

Pin Number	Primary Pin Name	Primary Electrical Type	Alternate Pin Name(s)
35	P36	I/O	SEG30
36	P35	I/O	SEG29
37	P34	I/O	SEG28
38	P33	I/O	SEG27/(PCLBUZ0)
39	P32	I/O	SEG26/(PCLBUZ1)
40	P31	I/O	SEG25/(TI06)/(TO06)
41	P30	I/O	SEG24/(TI07)/(TO07)
42	P77	I/O	SEG23/KR7/(INTP7)
43	P76	I/O	SEG22/KR6/(INTP6)
44	P75	I/O	SEG21/KR5/(INTP5)
45	P74	I/O	SEG20/KR4/(INTP4)
46	P73	I/O	SEG19/KR3/(INTP3)
47	P72	I/O	SEG18/KR2/(INTP2)
48	P71	I/O	SEG17/KR1/(INTP1)
49	P70	I/O	SEG16/KR0/(INTP0)
50	P83	I/O	SEG15
51	P82	I/O	SEG14/(SO10)/(TxD1)
52	P81	I/O	SEG13/(SI10)/(RxD1)/(SDA10)
53	P80	I/O	SEG12/(SCK10)/(SCL10)
54	EVSS1	Power	-
55	P17	I/O	SEG11/(SO00)/(TxD0)
56	P16	I/O	SEG10/(SI00)/(RxD0)/(SDA00)
57	P15	I/O	SEG9/(SCK00)/(SCL00)
58	P14	I/O	SEG8
59	P13	I/O	SEG7
60	P12	I/O	SEG6
61	P11	I/O	SEG5
62	P10	I/O	SEG4
63	EVDD1	Power	-
64	COM7	Output	SEG3
65	COM6	Output	SEG2
66	COM5	Output	SEG1
67	COM4	Output	SEG0
68	COM3	Output	-
69	COM2	Output	-
70	COM1	Output	-
71	COM0	Output	-
72	P85	I/O	SEG41/SO30/TxD3
73	P84	I/O	SEG40/SI30/RxD3/SDA30
74	P57	I/O	SEG39/SCK30/SCL30
75	P56	I/O	SEG38/TxD2/IrTxD
76	P55	I/O	SEG37/RxD2/IrRxD
77	P54	I/O	SEG36
78	P53	I/O	SEG35
79	P52	I/O	SEG34
80	P51	I/O	SEG33
81	P50	I/O	SEG32
82	ANIP3	Input	-
83	ANIN3	Input	-
84	ANIP2	Input	-
85	ANIN2	Input	-
86	AVRT	Power	-
87	AVCM	Power	-
88	AVSS	Power	-
89	AREGC	Power	-
90	ANIP1	Input	-
91	ANIN1	Input	-
92	ANIP0	Input	-
93	ANIN0	Input	-
94	P25	I/O	ANI5
95	P24	I/O	ANI4
96	P23	I/O	ANI3

Pin Number	Primary Pin Name	Primary Electrical Type	Alternate Pin Name(s)
97	P22	I/O	ANI2/EXLVD
98	P21	I/O	AVREFM/ANI1
99	P20	I/O	AVREFP/ANI0
100	P07	I/O	SO00/TxD0/TI02/TO02/INTP2/TOOLTxD

### A.2.2 64-LFQFP

Pin Number	Primary Pin Name	Primary Electrical Type	Alternate Pin Name(s)
1	P07	I/O	SO00/TxD0/TI02/TO02/INTP2/TOOLTxD
2	P06	I/O	SI00/RxD0/SDA00/TI03/TO03/INTP4/TOOLRxD
3	P05	I/O	SCK00/SCL00/TI04/TO04/INTP3
4	P43	I/O	TI00/TO00/PCLBUZ0/RTCOUT
5	P40	I/O	TOOL0
6	\RESET	Input	-
7	P122	Input	X2/EXCLK
8	P121	Input	X1
9	P137	Input	INTP0
10	P124	Input	XT2/EXCLKS
11	P123	Input	XT1
12	VRTC	Power	-
13	REGC	Power	-
14	VSS	Power	EVSS0
15	VDD	Power	EVDD0
16	VBAT	Power	-
17	P60	I/O	SCLA0/(TI00)/(TO00)
18	P61	I/O	SDAA0/(TI01)/(TO01)
19	P62	I/O	(TI02)/(TO02)/(RTCOUT)
20	P127	I/O	CAPH/(TI03)/(TO03)
21	P126	I/O	CAPL/(TI04)/(TO04)
22	VL1	Power	-
23	VL2	Power	-
24	VL4	Power	-
25	P125	I/O	VL3/INTP1/TI05/TO05/PCLBUZ1
26	P31	I/O	SEG25/TxD2/IrTxD/TI06/TO06
27	P30	I/O	SEG24/RxD2/IrRxD/TI07/TO07/INTP5
28	P74	I/O	SEG20/KR4/(INTP4)/(PCLBUZ0)
29	P73	I/O	SEG19/KR3/(INTP3)/(PCLBUZ1)
30	P72	I/O	SEG18/KR2/TI01/TO01/(INTP2)
31	P71	I/O	SEG17/KR1/(INTP1)
32	P70	I/O	SEG16/KR0/(INTP0)
33	P17	I/O	SEG11/(SO00)/(TxD0)
34	P16	I/O	SEG10/INTP7/(SI00)/(RxD0)/(SDA00)
35	P15	I/O	SEG9/(SCK00)/(SCL00)
36	P14	I/O	SEG8/SO10/TxD1
37	P13	I/O	SEG7/SI10/RxD1/SDA10/INTP6
38	P12	I/O	SEG6/SCK10/SCL10
39	P11	I/O	SEG5
40	P10	I/O	SEG4
41	COM7	Output	SEG3
42	COM6	Output	SEG2
43	COM5	Output	SEG1
44	COM4	Output	SEG0
45	COM3	Output	-
46	COM2	Output	-
47	COM1	Output	-
48	COM0	Output	-
49	ANIP3	Input	-
50	ANIN3	Input	-
51	ANIP2	Input	-
52	ANIN2	Input	-
53	AVRT	Power	-
54	AVCM	Power	-

Pin Number	Primary Pin Name	Primary Electrical Type	Alternate Pin Name(s)
55	AVSS	Power	-
56	AREGC	Power	-
57	ANIP1	Input	-
58	ANIN1	Input	-
59	ANIPO	Input	-
60	ANINO	Input	-
61	P23	I/O	ANI3
62	P22	I/O	ANI2/EXLVD
63	P21	I/O	AVREFM/ANI1
64	P20	I/O	AVREFP/ANI0

### A.2.3 80-LFQFP

Pin Number	Primary Pin Name	Primary Electrical Type	Alternate Pin Name(s)
1	P55	I/O	RxD2/IrRxD
2	P41	I/O	INTP6/TI01/TO01/PCLBUZ1
3	P40	I/O	TOOL0
4	P152	I/O	RTCIC2
5	P151	I/O	RTCIC1
6	P150	I/O	RTCCOUT/RTCIC0
7	\RESET	Input	-
8	P122	Input	X2/EXCLK
9	P121	Input	X1
10	P137	Input	INTP0
11	P124	Input	XT2/EXCLKS
12	P123	Input	XT1
13	VRTC	Power	-
14	REGC	Power	-
15	VSS	Power	EVSS0
16	VDD	Power	-
17	EVDD0	Power	-
18	VBAT	Power	-
19	P60	I/O	SCLA0/(TI00)/(TO00)
20	P61	I/O	SDAA0/(TI01)/(TO01)
21	P62	I/O	(TI02)/(TO02)/(RTCCOUT)
22	P127	I/O	CAPH/(TI03)/(TO03)
23	P126	I/O	CAPL/(TI04)/(TO04)
24	VL1	Power	-
25	VL2	Power	-
26	VL4	Power	-
27	P125	I/O	VL3/INTP1/(TI05)/(TO05)
28	P33	I/O	SEG27/(PCLBUZ0)
29	P32	I/O	SEG26/(PCLBUZ1)
30	P31	I/O	SEG25/(TI06)/(TO06)
31	P30	I/O	SEG24/(TI07)/(TO07)
32	P77	I/O	SEG23/KR7/(INTP7)
33	P76	I/O	SEG22/KR6/(INTP6)
34	P75	I/O	SEG21/KR5/(INTP5)
35	P74	I/O	SEG20/KR4/(INTP4)
36	P73	I/O	SEG19/KR3/(INTP3)
37	P72	I/O	SEG18/KR2/(INTP2)
38	P71	I/O	SEG17/KR1/(INTP1)
39	P70	I/O	SEG16/KR0/(INTP0)
40	P83	I/O	SEG15
41	P82	I/O	SEG14/(SO10)/(TxD1)
42	P81	I/O	SEG13/(SI10)/(RxD1)/(SDA10)
43	P80	I/O	SEG12/(SCK10)/(SCL10)
44	P17	I/O	SEG11/(SO00)/(TxD0)
45	P16	I/O	SEG10/(SI00)/(RxD0)/(SDA00)
46	P15	I/O	SEG9/(SCK00)/(SCL00)
47	P14	I/O	SEG8
48	P13	I/O	SEG7

Pin Number	Primary Pin Name	Primary Electrical Type	Alternate Pin Name(s)
49	P12	I/O	SEG6
50	P11	I/O	SEG5
51	P10	I/O	SEG4
52	COM7	Output	SEG3
53	COM6	Output	SEG2
54	COM5	Output	SEG1
55	COM4	Output	SEG0
56	COM3	Output	-
57	COM2	Output	-
58	COM1	Output	-
59	COM0	Output	-
60	P07	I/O	SO00/TxD0/TI02/TO02/INTP2/TOOLTxD/SEG37
61	P06	I/O	SI00/RxD0/SDA00/TI03/TO03/TOOLRxD/SEG36
62	P05	I/O	SCK00/SCL00/TI04/TO04/INTP3/SEG35
63	P04	I/O	SO10/TxD1/TI05/TO05/INTP4/SEG34
64	P03	I/O	SI10/RxD1/SDA10/TI06/TO06/SEG33
65	P02	I/O	SCK10/SCL10/TI07/TO07/INTP5/SEG32
66	ANIP2	Input	-
67	ANIN2	Input	-
68	AVRT	Power	-
69	AVCM	Power	-
70	AVSS	Power	-
71	AREGC	Power	-
72	ANIP1	Input	-
73	ANIN1	Input	-
74	ANIP0	Input	-
75	ANIN0	Input	-
76	P23	I/O	ANI3
77	P22	I/O	ANI2/EXLVD
78	P21	I/O	AVREFM/ANI1
79	P20	I/O	AVREFP/ANI0
80	P56	I/O	TxD2/IrTxD

#### A.2.4 80-LFQFP

Pin Number	Primary Pin Name	Primary Electrical Type	Alternate Pin Name(s)
1	P55	I/O	RxD2/IrRxD/RxDMG0/(INTP8)
2	P130	Output	PCLBUZ1/SMO02
3	P40	I/O	TOOL0/(RTCOUT)
4	P152	I/O	RTCIC2/INTP12
5	P151	I/O	RTCIC1/INTP13
6	P150	I/O	RTCOUT/RTCIC0/INTP14
7	RESET	Input	-
8	P122	Input	X2/EXCLK/INTP8
9	P121	Input	X1/INTP9
10	P137	Input	INTP0
11	P124	Input	XT2/EXCLKS
12	P123	Input	XT1
13	VRTC	Power	-
14	REGC	Power	-
15	VSS	Power	EVSS0/AVSS1
16	AVDD	Power	-
17	VDD	Power	EVDD0
18	LVDVBAT	Input	-
19	P60	I/O	SCLA0/(TI00)/(TO00)
20	P61	I/O	SDAA0/(TI01)/(TO01)
41	P82	I/O	SEG14/(SO10)/(TxD1)
42	P81	I/O	SEG13/(SI10)/(RxD1)/(SDA10)
43	P80	I/O	SEG12/(SCK10)/(SCL10)
44	P17	I/O	SEG11/(SO00)/(TxD0)
45	P16	I/O	SEG10/(SI00)/(RxD0)/(SDA00)

Pin Number	Primary Pin Name	Primary Electrical Type	Alternate Pin Name(s)
46	P15	I/O	SEG9/(SCK00)/(SCL00)
47	P14	I/O	SEG8
48	P13	I/O	SEG7
49	P12	I/O	SEG6
50	P11	I/O	SEG5
51	P10	I/O	SEG4
52	P97	I/O	COM7/SEG3
53	P96	I/O	COM6/SEG2
54	P95	I/O	COM5/SEG1
55	P94	I/O	COM4/SEG0
56	P93	I/O	COM3
57	P92	I/O	COM2
58	P91	I/O	COM1
59	P90	I/O	COM0
60	P07	I/O	SEG37/SO00/TxD0/TI02/TO02/INTP2/TOOLTxD/TxDMG1
61	P06	I/O	SEG36/SI00/RxD0/SDA00/TI03/TO03/TOOLRxD/RxDMG1/(INTP9)
61	P06	I/O	SEG36/SI00/RxD0/SDA00/TI03/TO03/TOOLRxD/RxDMG1/(INTP9)
62	P05	I/O	SEG35/SCK00/SCL00/TI04/TO04/INTP3/TRJIO0
62	P05	I/O	SEG35/SCK00/SCL00/TI04/TO04/INTP3/TRJIO0
63	P04	I/O	SEG34/SO10/TxD1/TI05/TO05/INTP4/TRJO0/SMO10
63	P04	I/O	SEG34/SO10/TxD1/TI05/TO05/INTP4/TRJO0/SMO10
64	P03	I/O	SEG33/SI10/RxD1/SDA10/TI06/TO06/TRJO1/SMO11
64	P03	I/O	SEG33/SI10/RxD1/SDA10/TI06/TO06/TRJO1/SMO11
65	P02	I/O	SEG32/SCK10/SCL10/TI07/TO07/INTP5/SMO12
65	P02	I/O	SEG32/SCK10/SCL10/TI07/TO07/INTP5/SMO12
66	ANIP2	Input	-
66	ANIP2	Input	-
67	ANIN2	Input	-
67	ANIN2	Input	-
68	AVRT	Power	-
68	AVRT	Power	-
69	AVCM	Power	-
69	AVCM	Power	-
70	AVSS0	Power	-
70	AVSS0	Power	-
71	AREGC	Power	-
71	AREGC	Power	-
72	ANIP1	Input	-
72	ANIP1	Input	-
73	ANIN1	Input	-
73	ANIN1	Input	-
74	ANIPO	Input	-
74	ANIPO	Input	-
75	ANINO	Input	-
75	ANINO	Input	-
76	P23	I/O	ANI0
76	P23	I/O	ANI0
77	P22	I/O	ANI5/EXLVD
77	P22	I/O	ANI5/EXLVD
78	P21	I/O	ANI4/AVREFM
78	P21	I/O	ANI4/AVREFM
79	P20	I/O	ANI3/AVREFP/VREFOUT
79	P20	I/O	ANI3/AVREFP/VREFOUT
80	P56	I/O	TxD2/IrTxD/TxDMG0
80	P56	I/O	TxD2/IrTxD/TxDMG0

### A.3 Symbol Parameters

Orderable Part Number	Min Input Voltage	Max Input Voltage	Max Output Frequency	Min Operating Temperature	Max Operating Temperature	RAM Size	Memory Size	Interface	Number of ADC Channels	Number of I2C Channels	Number of SPI Channels	Number of UART Channels	Number of Timers/Counters
R5F10NLEDFB #75	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	6 KB	64 KB	I2C, SPI, UART	10-bit X 4-Ch	3	2	3	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F10NLGDFB#75	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	8 KB	128 KB	I2C, SPI, UART	10-bit X 4-Ch	3	2	3	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F10NMEDFB#75	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	6 KB	64 KB	I2C, SPI, UART	10-bit X 4-Ch	3	2	3	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F10NMGDFB#75	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	8 KB	128 KB	I2C, SPI, UART	10-bit X 4-Ch	3	2	3	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F10NMJDFB#75	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	16 KB	256 KB	I2C, SPI, UART	10-bit X 4-Ch	3	2	3	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F10NMLDFB#70	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	-	-	I2C, SPI, UART	10-bit X 4-Ch	3	2	3	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F10NPGDFB#75	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	8 KB	128 KB	I2C, SPI, UART	10-bit X 6-Ch	4	3	4	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F10NPJDFB #75	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	16 KB	256 KB	I2C, SPI, UART	10-bit X 6-Ch	4	3	4	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F10NPLDFB#70	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	-	-	I2C, SPI, UART	10-bit X 6-Ch	4	3	4	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F11TLEDFB #75	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	6 KB	64 KB	I2C, SPI, UART	10-bit X 4-Ch	3	2	3	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch
R5F11TLGDFB #75	1.7 V	5.5 V	32 MHz	-40 °C	+85 °C	8 KB	128 KB	I2C, SPI, UART	10-bit X 4-Ch	3	2	3	16-bit X 10-Ch, 12-bit X 1-Ch, 8-bit X 4-Ch

## A.4 Footprint Design Information

### A.4.1 80-LQFP


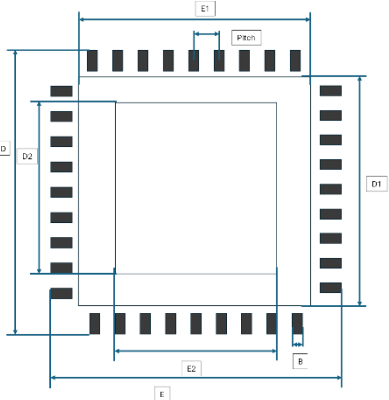
IPC Footprint Type	Package Code/ POD number	Number of Pins
QFP	PLQP0080KB-B	80

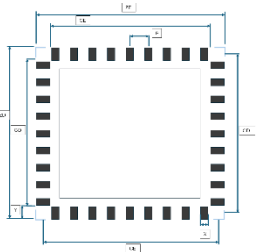
Description	Dimension	Value (mm)	Diagram
Minimum lead span (vertical side)	Dmin	14.2	<p>The diagram shows a square footprint with pins on all four sides. Dimensions are labeled: D (total width), D1 (inner width), D2 (inner height), E (total length), E1 (inner length), E2 (inner width), B (pin width), and Pitch (distance between pins).</p>
Maximum lead span (vertical side)	Dmax	14.2	
Minimum lead span (horizontal side)	Emin	14.2	
Maximum lead span (horizontal side)	Emax	14.2	
Minimum body span (vertical side)	D1min	12.1	
Maximum body span (vertical side)	D1max	12.1	
Minimum body span (horizontal side)	E1min	12.1	
Maximum body span (horizontal side)	E1max	12.1	
Minimum Lead Width	Bmin	0.2	
Maximum Lead Width	Bmax	0.2	
Minimum Lead Length	Lmin	0.45	
Maximum Lead Length	Lmax	0.75	
Maximum Height	Amax	1.7	<p>The diagram shows a side view of the package. Dimensions are labeled: Amax (maximum height), A1min (minimum standoff height), L (lead length), and PinCountD (number of pins on the vertical side).</p>
Minimum Standoff Height	A1min	0	
Minimum Lead Thickness	cmin	-	
Maximum Lead Thickness	cmax	-	
Number of pins (vertical side)	PinCountD	20	
Number of pins (horizontal side)	PinCountE	20	
Distance between the center of any two adjacent pins	Pitch	0.5	
Location of pin 1; S2 = corner of D side, C1 = center of E side	Pin1	S2	
Minimum thermal pad size (vertical side)	D2min	-	
Maximum thermal pad size (vertical side)	D2max	-	
Minimum thermal pad size (horizontal side)	E2min	-	
Maximum thermal pad size (horizontal side)	E2max	-	

Recommended Land Pattern (NSMD Design)			
Description	Dimension	Value (mm)	Diagram
Distance between left pad toe to right pad toe (horizontal side)	ZE	-	<p>The diagram shows a square footprint with pins on all four sides. Dimensions are labeled: ZE (distance between left pad toe to right pad toe), ZD (distance between top pad toe to bottom pad toe), GE (distance between left pad heel to right pad heel), GD (distance between top pad heel to bottom pad heel), X (pad width), and Y (pad length).</p>
Distance between top pad toe to bottom pad toe (vertical side)	ZD	-	
Distance between left pad heel to right pad heel (horizontal side)	GE	-	
Distance between top pad heel to bottom pad heel (vertical side)	GD	-	
Pad Width	X	-	
Pad Length	Y	-	



IPC Footprint Type	Package Code/ POD number	Number of Pins
QFP	-	-

Description	Dimension	Value (mm)	Diagram
Minimum lead span (vertical side)	Dmin	-	
Maximum lead span (vertical side)	Dmax	-	
Minimum lead span (horizontal side)	Emin	-	
Maximum lead span (horizontal side)	Emax	-	
Minimum body span (vertical side)	D1min	-	
Maximum body span (vertical side)	D1max	-	
Minimum body span (horizontal side)	E1min	-	
Maximum body span (horizontal side)	E1max	-	
Minimum Lead Width	Bmin	-	
Maximum Lead Width	Bmax	-	
Minimum Lead Length	Lmin	-	
Maximum Lead Length	Lmax	-	
Maximum Height	Amax	-	
Minimum Standoff Height	A1min	-	
Minimum Lead Thickness	cmin	-	
Maximum Lead Thickness	cmax	-	
Number of pins (vertical side)	PinCountD	-	
Number of pins (horizontal side)	PinCountE	-	
Distance between the center of any two adjacent pins	Pitch	-	
Location of pin 1; S2 = corner of D side, C1 = center of E side	Pin1	-	
Minimum thermal pad size (vertical side)	D2min	-	
Maximum thermal pad size (vertical side)	D2max	-	
Minimum thermal pad size (horizontal side)	E2min	-	
Maximum thermal pad size (horizontal side)	E2max	-	

Recommended Land Pattern (NSMD Design)			
Description	Dimension	Value (mm)	Diagram
Distance between left pad toe to right pad toe (horizontal side)	ZE	-	
Distance between top pad toe to bottom pad toe (vertical side)	ZD	-	
Distance between left pad heel to right pad heel (horizontal side)	GE	-	
Distance between top pad heel to bottom pad heel (vertical side)	GD	-	
Pad Width	X	-	
Pad Length	Y	-	

## A.4.2 100-LQFP

IPC Footprint Type	Package Code/ POD number	Number of Pins
QFP	PLQP0100KB-B	100

Description	Dimension	Value (mm)	Diagram
Minimum lead span (vertical side)	Dmin	15.8	
Maximum lead span (vertical side)	Dmax	16.2	
Minimum lead span (horizontal side)	Emin	15.8	
Maximum lead span (horizontal side)	Emax	16.2	
Minimum body span (vertical side)	D1min	13.9	
Maximum body span (vertical side)	D1max	14.1	
Minimum body span (horizontal side)	E1min	13.9	
Maximum body span (horizontal side)	E1max	14.1	
Minimum Lead Width	Bmin	0.15	
Maximum Lead Width	Bmax	0.27	
Minimum Lead Length	Lmin	0.45	
Maximum Lead Length	Lmax	0.75	
Maximum Height	Amax	1.7	
Minimum Standoff Height	A1min	0	
Minimum Lead Thickness	cmin	-	
Maximum Lead Thickness	cmax	-	
Number of pins (vertical side)	PinCountD	25	
Number of pins (horizontal side)	PinCountE	25	
Distance between the center of any two adjacent pins	Pitch	0.5	
Location of pin 1; S2 = corner of D side, C1 = center of E side	Pin1	S2	
Minimum thermal pad size (vertical side)	D2min	-	
Maximum thermal pad size (vertical side)	D2max	-	
Minimum thermal pad size (horizontal side)	E2min	-	
Maximum thermal pad size (horizontal side)	E2max	-	

Recommended Land Pattern (NSMD Design)			
Description	Dimension	Value (mm)	Diagram
Distance between left pad toe to right pad toe (horizontal side)	ZE	-	
Distance between top pad toe to bottom pad toe (vertical side)	ZD	-	
Distance between left pad heel to right pad heel (horizontal side)	GE	-	
Distance between top pad heel to bottom pad heel (vertical side)	GD	-	
Pad Width	X	-	
Pad Length	Y	-	

### A.4.3 64-LQFP

IPC Footprint Type	Package Code/ POD number	Number of Pins
QFP	PLQP0064KC-A	64

Description	Dimension	Value (mm)	Diagram
Minimum lead span (vertical side)	Dmin	11.8	<p>The diagram shows a square package footprint with pins on all four sides. Key dimensions labeled include E1 (top lead span), E2 (bottom lead span), D1 (right lead span), D2 (left lead span), B (pin width), and Pitch (distance between pins).</p>
Maximum lead span (vertical side)	Dmax	12.2	
Minimum lead span (horizontal side)	Emin	11.8	
Maximum lead span (horizontal side)	Emax	12.2	
Minimum body span (vertical side)	D1min	10	
Maximum body span (vertical side)	D1max	10	
Minimum body span (horizontal side)	E1min	10	
Maximum body span (horizontal side)	E1max	10	
Minimum Lead Width	Bmin	0.17	
Maximum Lead Width	Bmax	0.27	
Minimum Lead Length	Lmin	0.3	
Maximum Lead Length	Lmax	0.7	
Maximum Height	Amax	1.7	<p>The diagram shows a side view of the package footprint. Key dimensions labeled include Amax (maximum height), A1min (minimum standoff height), L (lead length), and PinCountD (number of pins on the vertical side).</p>
Minimum Standoff Height	A1min	0	
Minimum Lead Thickness	cmin	0.12	
Maximum Lead Thickness	cmax	0.22	
Number of pins (vertical side)	PinCountD	16	
Number of pins (horizontal side)	PinCountE	16	
Distance between the center of any two adjacent pins	Pitch	0.5	
Location of pin 1; S2 = corner of D side, C1 = center of E side	Pin1	S2	
Minimum thermal pad size (vertical side)	D2min	-	
Maximum thermal pad size (vertical side)	D2max	-	
Minimum thermal pad size (horizontal side)	E2min	-	
Maximum thermal pad size (horizontal side)	E2max	-	

Recommended Land Pattern (NSMD Design)			
Description	Dimension	Value (mm)	Diagram
Distance between left pad toe to right pad toe (horizontal side)	ZE	-	<p>The diagram shows the recommended land pattern for the 64-LQFP package footprint. Key dimensions labeled include ZE (distance between left pad toe to right pad toe), ZD (distance between top pad toe to bottom pad toe), GE (distance between left pad heel to right pad heel), GD (distance between top pad heel to bottom pad heel), X (pad width), and Y (pad length).</p>
Distance between top pad toe to bottom pad toe (vertical side)	ZD	-	
Distance between left pad heel to right pad heel (horizontal side)	GE	-	
Distance between top pad heel to bottom pad heel (vertical side)	GD	-	
Pad Width	X	-	
Pad Length	Y	-	